

REMARKS/ARGUMENTS

Favorable consideration of this application as presently amended and in light of the following remarks is respectfully requested.

Claims 9-14 and 19 are active in this application, Claims 9 and 13 have been amended and new Claim 19 added by the present amendment.

In the outstanding Official Action, Claim 13 was objected to as including informalities requiring correction, Claims 9-11 were rejected under 35 USC §102(b) as being anticipated by Yoshida et al (U.S. 5,164,632), Claims 12 and 14 were rejected under 35 USC §103(a) as being unpatentable over Yoshida et al in view of Jin et al (U.S. 5,648,699), and Claim 13 was rejected under 35 USC §103(a) as being unpatentable over “Jin et al” [sic: Yoshida et al] in view of Jin et al and in further view of Terai et al (U.S. 3,935,349).

In response to the objection to Claim 13, the informalities noted have been corrected herewith, and the outstanding objection is believed to have been overcome.

In light of the several grounds for rejection, Claim 9 has been amended to clarify a feature of the present invention. To that end, amended Claim 9 clarifies that the recited “subjecting” step results a number of small through holes, --each of which opens to both surfaces of the metal substrate--. This amendatory language is believed to find clear support in the disclosure as originally filed, for example as shown in Figures 2 and 3 and by virtue of terminology (“through holes”) itself, and is not believed to raise a question of new matter.

Recapitulating, amended Claim 9, consistent with the description at page 12, line 16 to page 19, line 9 of the specification, recites,

A method of manufacturing an electron source device, comprising:
subjecting a metal substrate to electrolytic oxidation, thereby forming
an oxide substrate having a number of small through holes, each of which
opens to both surfaces of the metal substrate;
burying an electron-emitting material in the through holes of the oxide
substrate;
forming a first electrode on one surface of the oxide substrate, said first
electrode contacting the electron-emitting material; and

forming a second electrode on another surface of the oxide substrate, said second electrode insulated from the electron-emitting material.

It is respectfully submitted that none of the cited reference discloses or obviates the claimed invention.

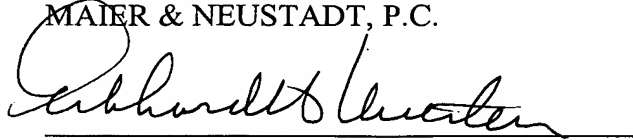
On the contrary, Yoshida et al. discloses an upper surface of an Al substrate is treated by anodic oxidation, as is clear from FIGS. 2 and 4 and the descriptions of column 3, lines 33-54. By this anodic oxidation process of the Al substrate, anodic oxidation film 11 of Al_2O_3 having a number of pores 11a is formed in the upper surface of the substrate to the thickness of 1 to 100 μm . Pores 11a are, however, bores having bottoms, and are not through holes open to both surfaces of the substrate. In Yoshida et al., the Al portion is removed after Au is deposited in pores 11a, as shown in the descriptions of FIGS. 5 and 6 and column 3, lines 55-62. Thus, Yoshida et al. discloses a method much different from the claimed invention. Therefore, it is respectfully submitted that amended Claim 9 patentably defines over Yoshida et al. Further, it is respectfully submitted that the secondary references cited in the several grounds for rejection fail to cure the deficiencies in the Yoshida et al. reference and that amended Claim 1 is therefore allowable.

Similarly, Claim 19 recites a method of manufacturing an electron source device and includes a similar "subjecting" step as recited in Claim 1, in which a number of through holes are formed in a metal substrate having first and second surfaces, and --each of [the through holes] includes a first opening open to the first surface and a second opening open to the second surface--. Claim 19 is therefore also believed to be patentably distinguishing over the cited art and also allowable.

Consequently, in view of the foregoing discussion and present amendment, it is believed that no further issues are outstanding, and it is respectfully submitted that this application is in condition for formal allowance. An early and favorable action is therefore respectfully requested.

Respectfully submitted,

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